



BRIGHTTEK
BRIGHTTEK (EUROPE) LIMITED

Brighten Up The World With LED!



ISO/TS 16949:2009



BS EN ISO 14001:2004



QC 080000 IECQ HSPM

PRODUCT DATASHEET



- ▶ PLCC6 SMD
- ▶ 5050 1.6t Series
- ▶ Sky White / Ice Blue

NOW42S53



Release Date: 03 June 2022 Version: A1.1



5050 1.6t Series

RoHS
Compliant



FEATURES:

- **Package:** PLCC2 White SMD Package
- **Forward Current:** 20mA*3
- **Forward Voltage (typ.):** 3.2V
- **Luminous Flux (typ.):** 22.5lm/7200mcd@60mA
- **Colour:** Sky White / Ice Blue
- **Colour Temperature (CCT):** 9900~25000K
- **Viewing angle:** 120°
- **Materials:**
 - Die: InGaN
 - Resin: Silicon (Yellow Diffused)
 - L/T Finish: Ag plated
- **Operating Temperature:** -40~+85°C
- **Storage Temperature:** -40~+100°C
- **Grouping parameters:**
 - Forward Voltage
 - Luminous Intensity
 - CIE Chromaticity
- **Soldering methods:** Reflow Soldering
- **MSL Level:** MSL 5 according to JEDEC
- **Packing:** 12mm tape with max.1000/reel, ø180mm (7")

APPLICATIONS:

- General Lighting
- Portable Lighting
- Commercial Lighting
- Indoor Lighting
- Backlight for LCD

CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
DC Forward Current	I _F	30*3	mA
Pulse Forward Current (Duty 1/10, width 0.1ms)	I _{PF}	100*3	mA
Reverse Voltage	V _R	5	V
Reverse Current @5V	I _R	10	μA
Operating Temperature	T _{OPR}	-40~+85	°C
Storage Temperature	T _{STG}	-40~+100	°C
Electrostatic Discharge (HBM)	ESD	1	kV
Junction Temperature	T _J	110	°C
Colour Rendering Index (typ)	CRI	70	---

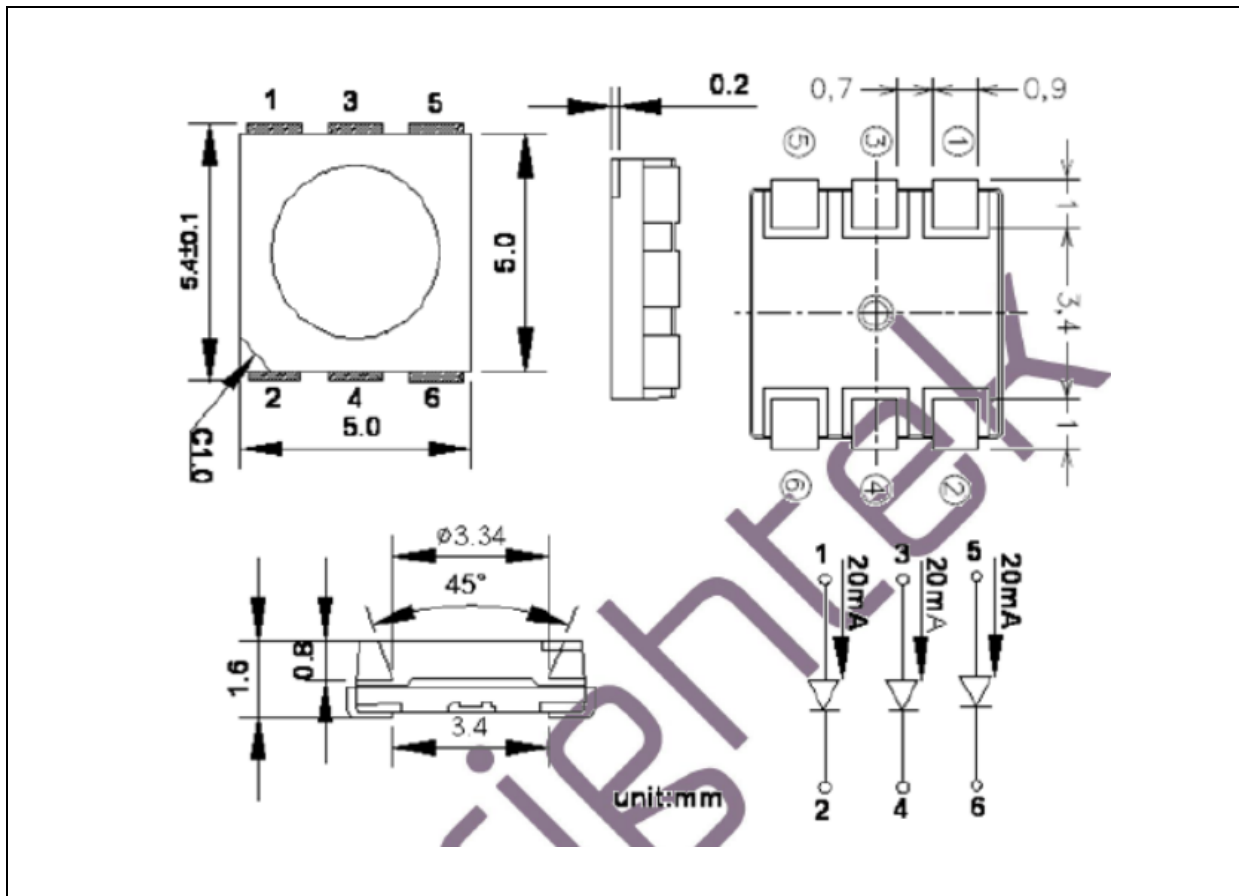
Electrical & Optical Characteristics (Ta=25°C)

Parameter	Symbol	Values			Unit	Test Condition
		Min.	Typ.	Max.		
Forward Voltage	V _F	2.8	3.2	3.6	V	I _F =20mA*3
Luminous Intensity	I _v	4600	7200	---	mcd	I _F =20mA*3
Luminous Flux	Φ _v	---	22.5	---	lm	I _F =20mA*3
Chromaticity Coordinates	X	---	0.2726	---	---	I _F =20mA*3
	Y	---	0.2598	---		
Colour Temperature	CCT	9900	---	25000	K	I _F =20mA*3
Viewing Angle	2θ _{1/2}	---	120	---	deg	I _F =20mA*3

1. Luminous flux (Φ_v) ±10%, Forward Voltage (V_F) ±0.1V

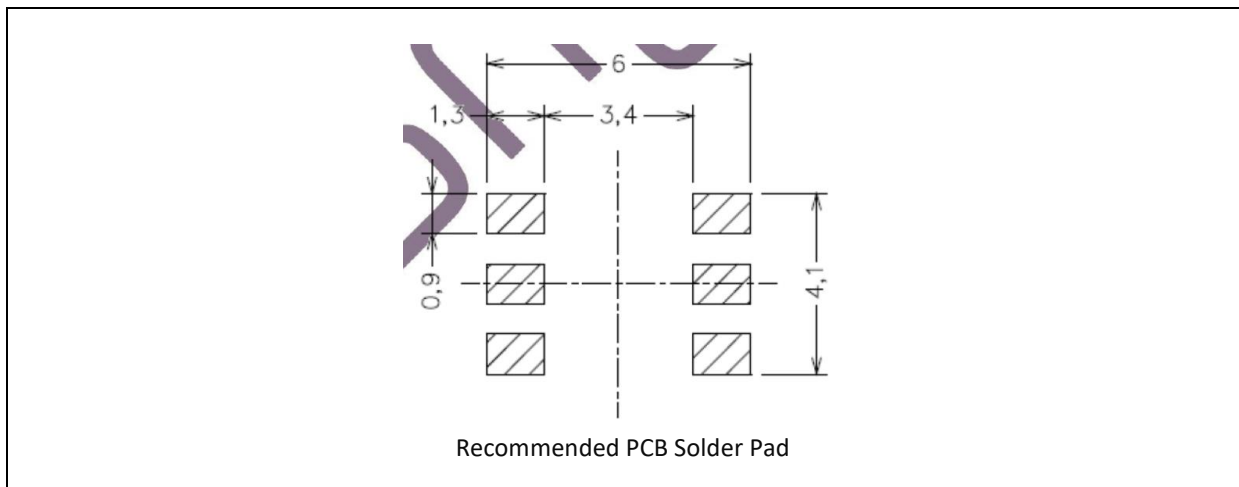
OUTLINE DIMENSION:

Package Dimension:



1. All dimensions are in millimetre (mm).
2. Tolerance ± 0.13 mm, unless otherwise noted.

Recommended Soldering Pad Dimension:



1. Dimensions are in millimetre (mm).
2. Tolerance ± 0.1 mm with angle tolerance $\pm 0.5^\circ$.

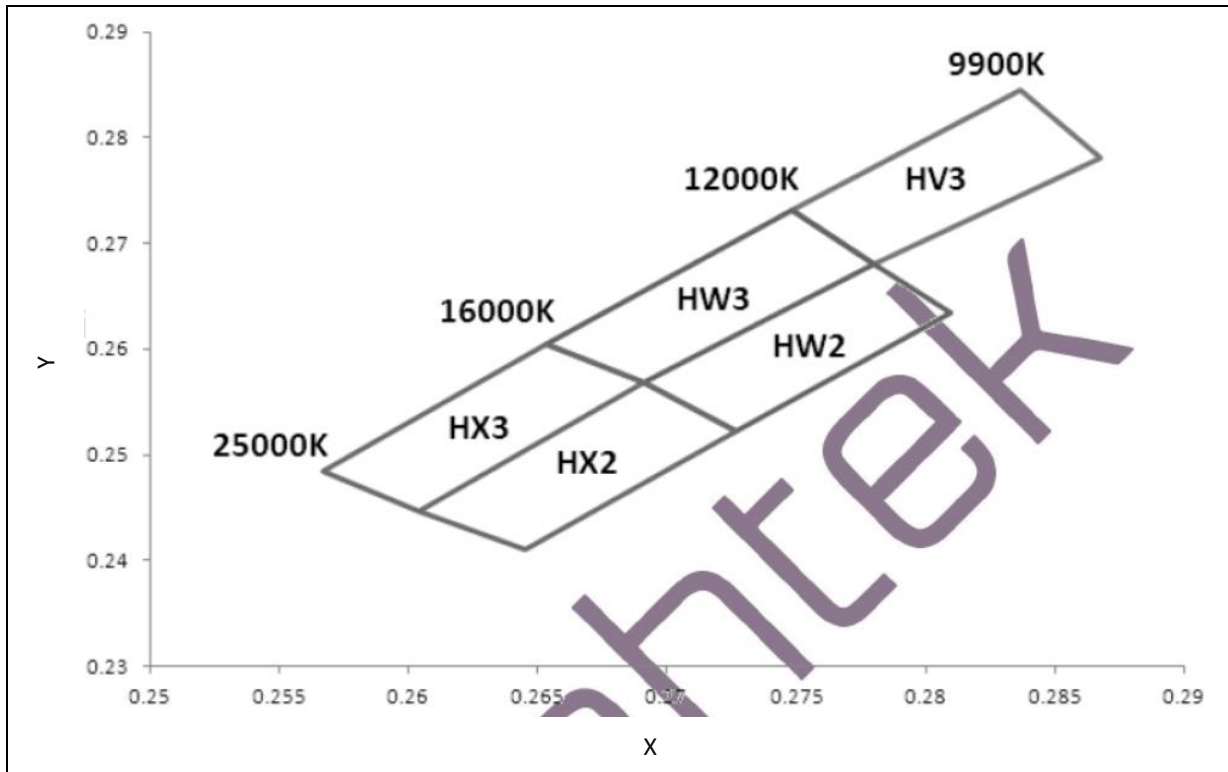
BINNING GROUPS:

 Forward Voltage Classifications ($I_F = 20\text{mA} \times 3$):

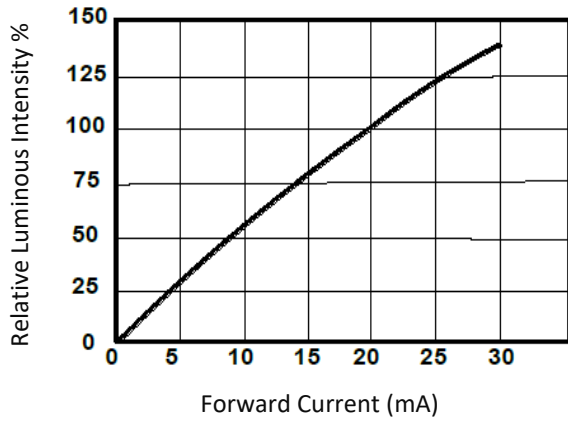
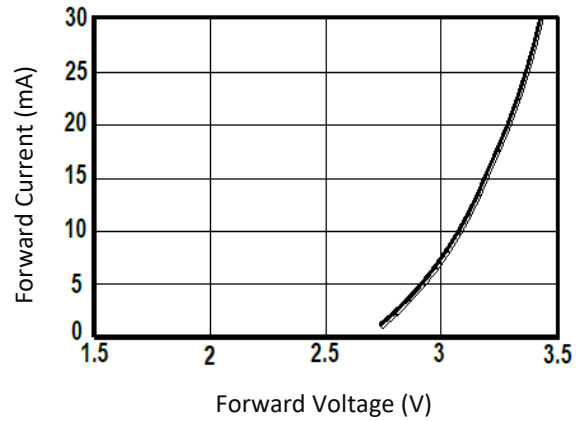
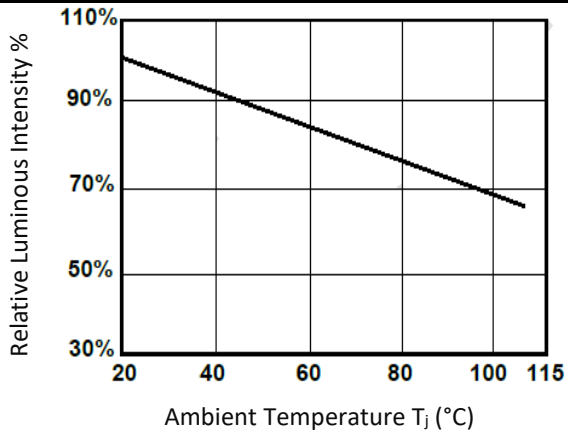
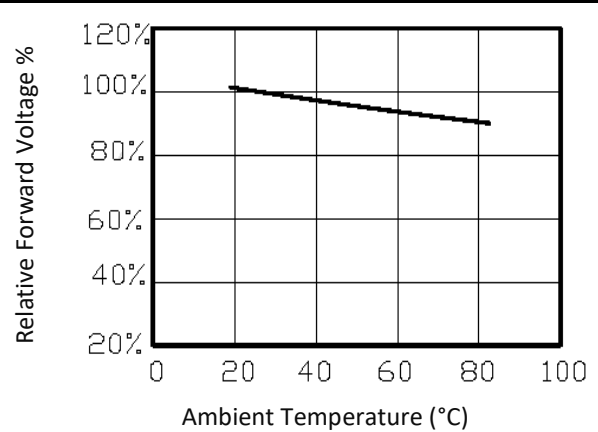
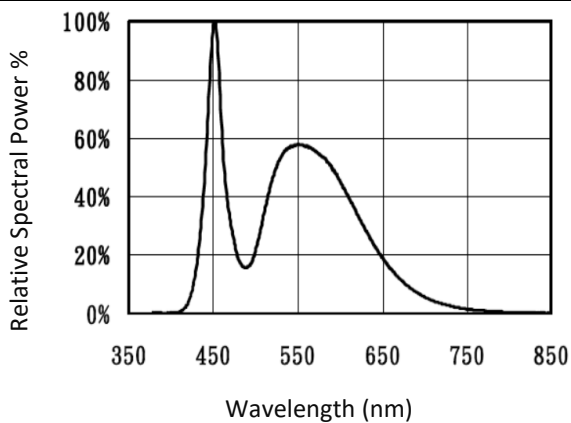
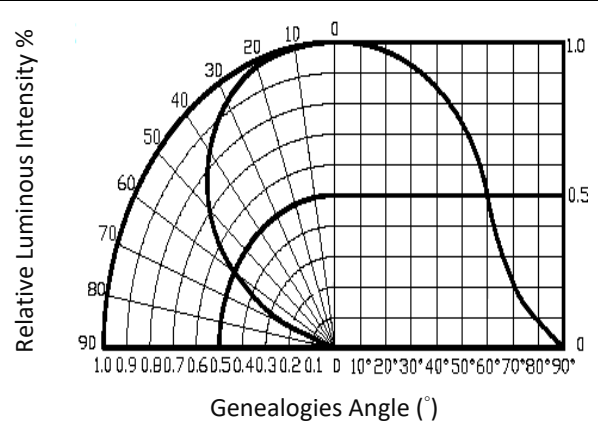
Code	Min.	Max.	Unit
B	2.8	2.9	V
C	2.9	3.0	
D	3.0	3.1	
E	3.1	3.2	
F	3.2	3.3	
G	3.3	3.4	
H	3.4	3.5	
I	3.5	3.6	

 Luminous Intensity Classifications ($I_F = 20\text{mA} \times 3$):

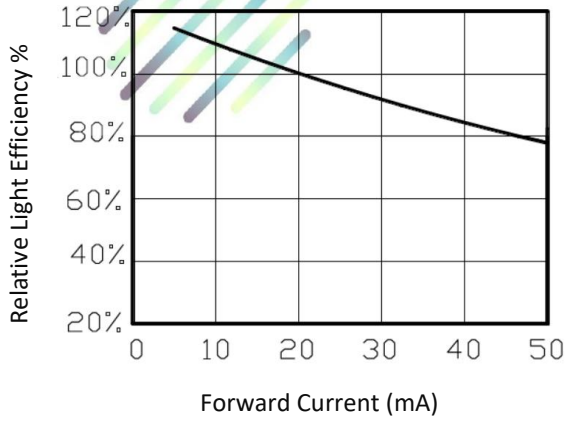
Code	Min.	Max.	Unit
21	4600	6000	lm
22	6000	7800	
23	7800	10100	

CIE CHROMATICITY DIAGRAM:

 Chromaticity Coordinates Classifications ($I_F = 20\text{mA} \cdot 3$):

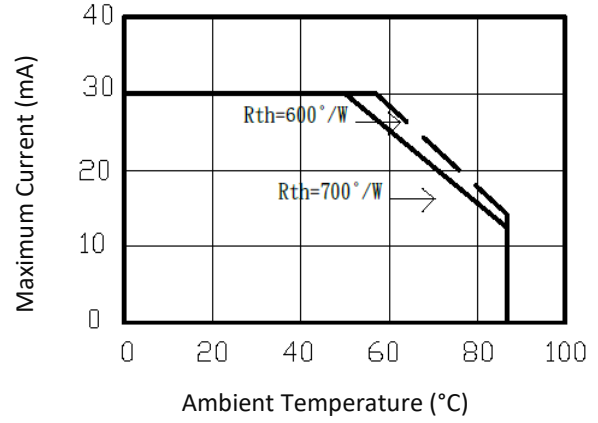
	1		2		3		4	
	X	Y	X	Y	X	Y	X	Y
HV3	0.2748	0.2732	0.2780	0.2680	0.2868	0.2781	0.2837	0.2845
HW2	0.2691	0.2568	0.2727	0.2523	0.2810	0.2634	0.2780	0.2680
HW3	0.2653	0.2605	0.2691	0.2568	0.2780	0.2680	0.2748	0.2732
HX2	0.2604	0.2446	0.2645	0.2410	0.2727	0.2523	0.2691	0.2568
HX3	0.2567	0.2485	0.2604	0.2446	0.2691	0.2568	0.2653	0.2605

ELECTRO-OPTICAL CHARACTERISTICS:
Relative Luminous Intensity v.s. Forward Current

Forward Current v.s. Forward Voltage

Relative Luminous Intensity v.s. Ambient Temp.

Relative Forward Voltage v.s. Ambient Temp.

Relative Spectral Power v.s. Wavelength

Directive Radiation


Relative Light Efficiency v.s. Forward Current

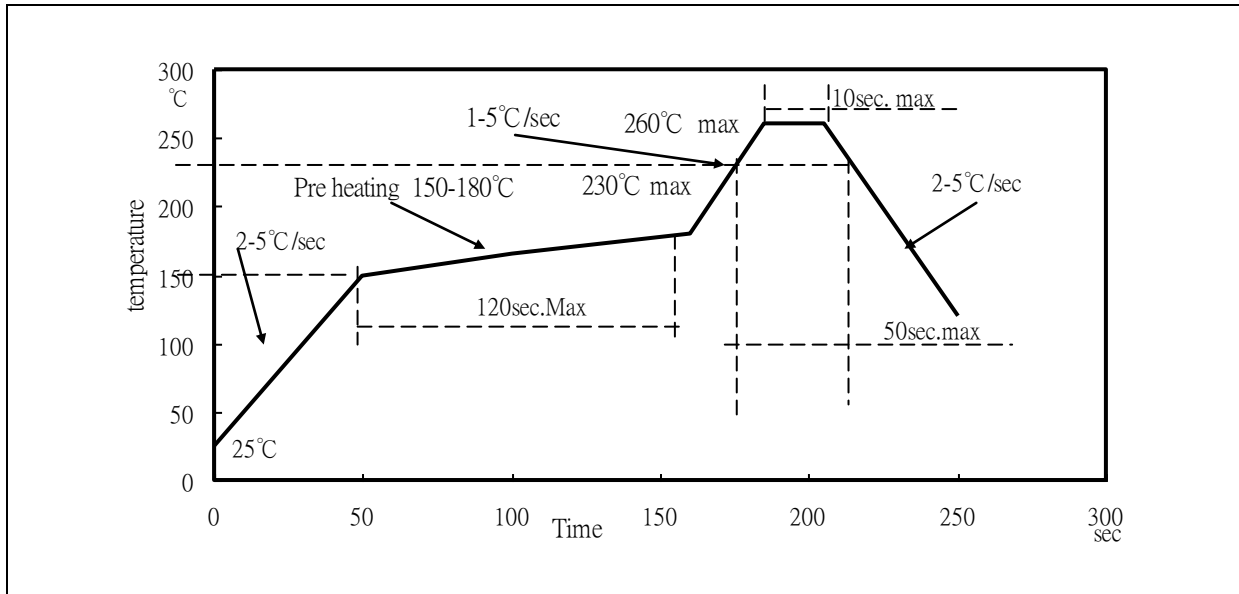


Forward Current Derating Curve



RECOMMENDED SOLDERING PROFILE:

IR Reflow Lead-free Solder:

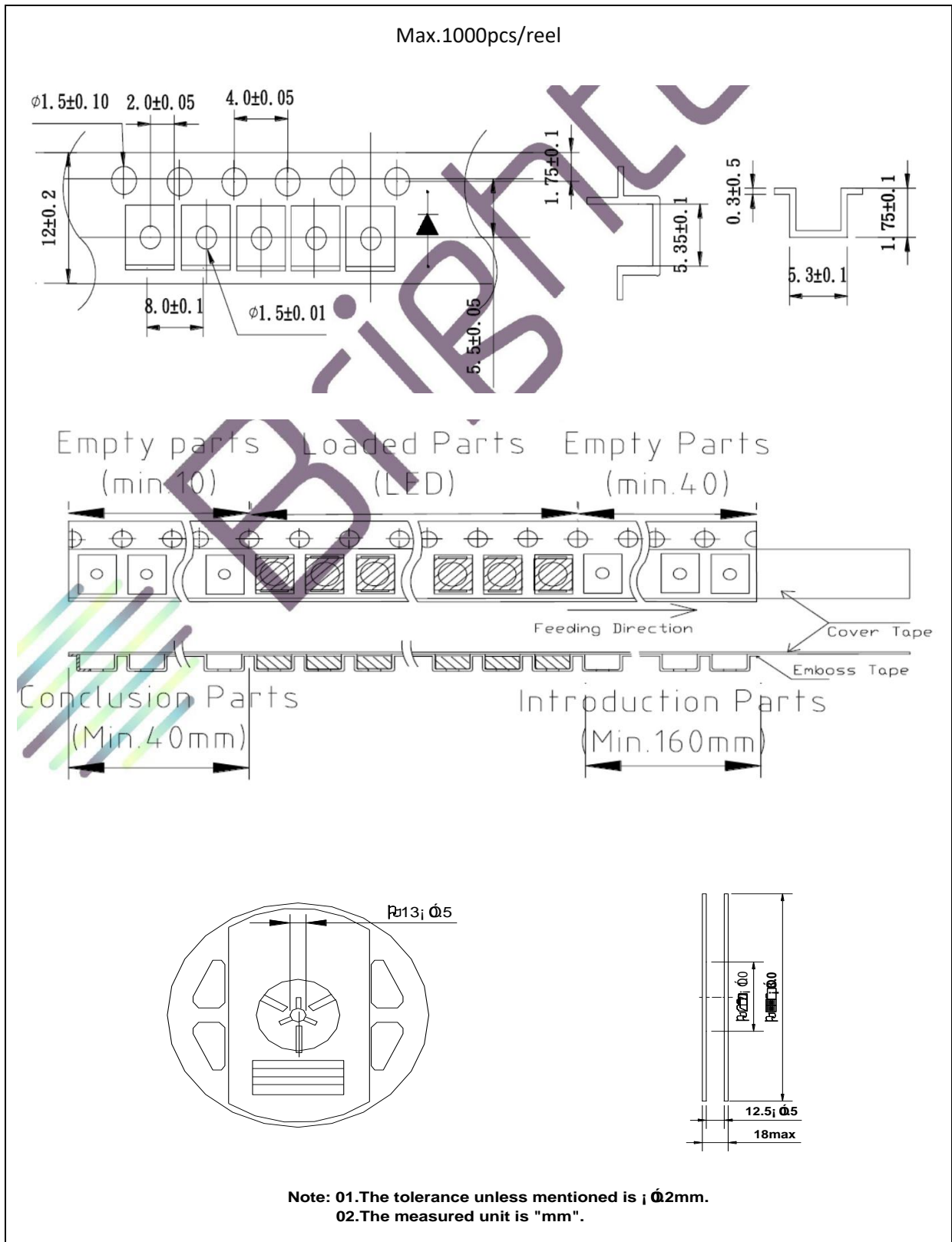


Note:

1. Maximum reflow soldering: 3 times.
2. Recommended reflow temperature: 240°C. Maximum soldering temperature should be limited to 260°C.
3. Before, during, and after soldering, should not apply stress on the components and PCB board.

PACKING SPECIFICATION:

Reel Dimension:



PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with desiccating agent <10% R.H. and apply baking.

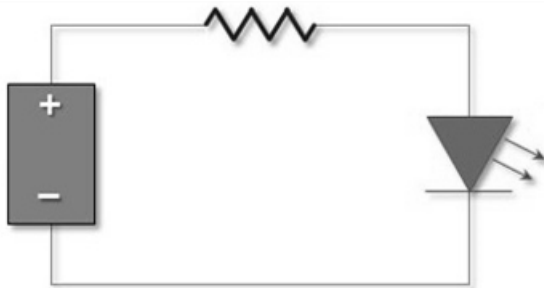
Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

- 60±3°C x 6hrs and <5%RH, reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handling the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.

REVISION RECORD:

Version	Date	Summary of Revision
A1.0	06/04/2017	Datasheet set-up.
A1.1	03/06/2022	New datasheet format.